NEWS FROM THE EIPC

EIPC WINTER CONFERENCE 2017

On February 2\textsuperscript{nd} & 3\textsuperscript{rd} 2017, the Wyndham Grand Hotel in Salzburg will be welcoming the many delegates to the EIPC Winter Conference which is to be held there next year. With a focus on the present and the future, the format of the Conference will be based on proven recipes, combining the look ahead from Walt Custer in his business outlook, to the impact of Moore’s Law (smaller faster cheaper) on the PCB industry and future electrical property needs.

The present will be looked after with their usual professional deliveries by speakers from such companies as Isola, Polar, Heraeus, Orbotech, Cicor, Optiprint & Schmoll. The world of the OEMs will be covered on the second day with speakers from AT&S and Ericsson. Safety, reliability, yield improvement, all are covered, and add into that the wealth of experience and knowledge of those speaking and those attending, and the mix is powerful.

Registration and further details are available from Carol Pelzers at EIPC on cpelzers@eipc.org

Photo: Tourismus Salzburg.
EIPC Winter Conference 2017
Date: February 2 & 3, 2017
Location: Wyndham Grand Hotel Salzburg
Salzburg, Austria
Bonus Programme: Visit Hangar 7;
Historical Flying Bulls aircraft fleet and Formula 1 race cars

Please note: numbers of visitors for the bonus programme are limited, on a first-
come, first-served basis, so make sure you are one of the first.

Day 1: 08:30-22:30 hrs.
- Welcome by EIPC Chairman, Alun Morgan
- Keynote Speech
- Session 1: New system designs and impact on material & processes
- Networking Lunch
- Session 2: Advanced Component and Attachment technologies for High
  First Pass Yields
- Session 3: Developments in Soldering and Solderable Finishes
- Bonus programme: Visit Hangar 7
- Networking dinner at Restaurant M32

Day 2: 09:00-14:15 hrs.
- Session 4: Future Electronic Application and Impact on Reliability and Safety
- Session 5: Reliability of PCBAs and PCBs
- Networking Lunch

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EIPC Winter Conference Salzburg, Austria, February 2 & 3, 2017


Programme
The European Electronics Association is extending an invitation to companies and individuals active in the Packaging and Interconnection Industry to participate in the EIPC Winter Conference to be held on February 2 & 3, 2017 in Salzburg, Austria. The aim of the Conference is to provide a platform for speakers and delegates to exchange information on market conditions and future innovation on interconnection and packaging. Delegates and visitors from throughout Europe will attend this event, offering presenters the opportunity to reach a targeted audience of decision makers and leaders of the international packaging and interconnection industry. This conference is an absolute ‘must’ for companies associated with PCB fabrication who wish to stay up to date with the latest market requirements, materials, fabrication equipment and manufacturing processes who also need to improve the efficiency of their processes and the reliability of their products.

Who should attend?
Engineers and decision-makers in the field of OEMs, EMS, assembly, and PCB fabricators as well as board and system designers at all levels are invited to participate. Circuit board designers, looking into more cost-effective solutions and miniaturisation, will learn about the developing trends in different applications. Board fabricators and development engineers will gain background information that will help to focus on more profitable products. Specialists and marketing managers will gain additional background data to focus on advanced PCB applications. OEMs will get a better understanding on how to get prepared for the next generation of electronic products.

Detailed information about the conference hotel
EIPC has chosen the Wyndham Grand Hotel Salzburg. The hotel is located in the city centre, 500m from the main station, 5km from the Salzburg airport. EIPC has negotiated a special rate for a single room of € 124.- per night, including breakfast. You can reserve your hotel room directly at the hotel by contacting the hotel at +43-662 4688 0 or info@wyndhamgrandsalzburg.com, please use the keywords ‘EIPC SALZBURG’. Reservations can be made until January 16, 2017. After this release date availability is on request.

Bonus Programme
On Thursday February 2, we will visit the Red Bull Hangar 7. We will go by coach from the conference hotel to Hangar 7. Hangar-7 at Salzburg Airport is a unique building which houses the historical Flying Bulls aircraft fleet and a collection of Formula 1 race cars. Hangar-7 also offers space for art exhibitions. More information is available on www.hangar-7.com

Networking Event
In the evening we will be having dinner all together at the excellent Restaurant M32. An opportunity to chat, gossip, enjoy good food and wine, and maybe learn something one didn’t know. As usual, this will be a convivial and sociable event open to conference delegates and their guests.

Table top exhibition and poster display area
During the Conference the EIPC will provide an opportunity for information sharing and discussion in a dedicated area. This will allow visitors to obtain latest product information and know how on an informal, or ‘one-to-one’ basis. A ‘poster wall’ and a table will be provided during the two days of the conference. If you are interested please download the registration form at www.eipc.org.

Conference Sponsoring
The EIPC offers several possibilities for sponsoring the EIPC Winter Conference Salzburg 2017. You can download the various possibilities that could be a great asset to your company’s exposure on the EIPC website or contact the EIPC office at kwestenberg@eipc.org

Sponsor of the EIPC Winter Conference Salzburg:

Press sponsors:
# Conference Programme Day 1, Thursday February 2

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<td>Welcome by the EIPC Chairman</td>
<td>Alun Morgan, EIPC, UK</td>
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<td>Keynote Speech - Business Outlook Global Electronics Industry</td>
<td>Walt Custer, Custer Consulting, USA</td>
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## Q & A

### Session 1: New system designs and impact on material & processes

**Moderator:**
Alun Morgan, EIPC, UK

- Systems design – Moore’s law and semiconductor industry changes, their effect and influences on PCB design
  - Nikola Kontic, Zuken, UK
- Influences of laminate and PCB Manufacturing tolerances on patch antenna and feed network characteristics
  - Alexander Ippich, Isola, DE

**Coffee break**

### PCB Technology Requirements for Millimeter-Wave Interconnect and Antenna

- Jim Francey, Optiprint, UK

### Ultra High Density Interconnect Printed Circuit Boards

- Karl-Heinz Fritz, Cicor, CH

### EMC conformal board design

- Prof. Rainer Thüringer (Chairman FED), TH-Mittelhessen, DE

**Panel discussion**

**Networking Lunch**

**Hotel Restaurant**

### Session 2: Advanced Component and Attachment technologies for High First Pass Yields

**Moderator:**
Christian Behrendt, Ilfa, DE

- Component trends, surface finishes trends and what is expected of first pass yield and what support is needed from suppliers in the industry
  - TBA
- Sinter paste for NiAu PCB Substrate with a pressure-less and low temperature process
  - Wolfgang Schmitt, Heraeus Electronics, DE
- Future electrical property needs drive Semi Additive Processes into high volume PCB manufacturing
  - Uwe Altmann, Orbotech SA, BE
- Registration, improving yield and reducing costs of the PCB manufacturing process
  - Stephan Kunz, Schmoll Maschinen, DE

**Panel discussion**

**Coffee break**

### Session 3: Developments in Soldering and Solderable Finishes

**Moderator:**
Martyn Gaudion, Polar Instruments, UK

- Reliability study of No Clean Chemistries for Lead Free solder paste in Vapour phase reflow
  - Stephen Teh, Inventec, FR
- Optimization of chemistry for a vapour phase process for defluxing No Clean lead free materials
  - Rodrigo Aguilar Limas, Inventec, FR
- Manufacturing Advanced Coatings for Future Electronic Systems (MACFEST)
  - Prof. Karl Ryder, University of Leicester, UK

**Panel discussion**

**Departure & Tour Red Bull Hangar 7**

**Dinner @ Restaurant M32**

**Return to Hotel**

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The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters. Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.
## Conference Programme Day 2, Friday February 3

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<td>Keynote Speech- PCB material toolbox for todays 3 and 4G networks and future 5G compliance</td>
<td>Stig Källman, Ericsson, SE</td>
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<td>Recognition in the view of a PCB manufacturer</td>
<td>Jürgen Deutschmann, AT&amp;S, AT</td>
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<td>UL PCB Recognition: A 20 minute guide to the UL 796 safety standard</td>
<td>Emma Hudson, UL, UK</td>
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<td>Heat spreading Mask / Mask for Direct Imaging</td>
<td>Don Monn, Taiyo, USA</td>
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<td>30 minutes Coffee break</td>
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<tr>
<td>Session 5: Reliability of PCBAs and PCBs</td>
<td>Moderator: Michael Weinhold, EIPC, DE</td>
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<td>Nondestructive Failure Analysis — Image and Reality. Matching findings (facts) with expectations (theories). Or not. Case studies from the coalface</td>
<td>Robert Mr. Boguski, Datest, USA</td>
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<td>Efficient test methods for prototype builds and small batch production in electronics assembly</td>
<td>Hermann Reischer, Polar Instruments, DE</td>
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<td>Tolerance requirements</td>
<td>TBA, Ilfa Feinstleiter Technologie, DE</td>
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Workshop Programme

09:30 h. Registration
10:00 h. Welcome & Introduction
   Dr Despina Moschou, University of Bath, UK
10:15 h. Current LOC fabrication technologies, integration challenges and beyond
   Dr Yuksel Temiz, IBM Research, Zurich Research Laboratory, CH
10:45 h. Lab-on-Chip standardisation and commercialisation challenges
   Dr Peter Hewkin, MF7 microfluidics consortium CEO, CiBi, Innovation Centre, UK
11:15 h. Fluidic systems in PCB-Technology, challenges and applications
   Prof Lienhard Pagel, Professor for Microsystems, Faculty of Computer Science and Electrical Engineering, University of Rostock, DE
11:45 h. Coffee break
12:00 h. PCB-based microfluidics for DNA amplification
   Dr Angeliki Tserepi, INN, NCSR Demokritos, GR
12:30 h. PCB-MEMS Devices and Systems for LOCs
   Prof Jose Manuel Quero, SOLAR MEMS Technologies, Electronic Engineering, University of Seville, ES
13:00 h. Lunch
14:00 h. Special requirements for fluidic PCB MEMS devices
   Prof Stefan Gassmann, Professor for Medical devices and Microtechnology, Jade University of Applied Sciences, Wilhelmshaven, DE
14:30 h. A biosensor on a PCB support
   Dr Maria Goreti Sales, BioMark-CINTESIS/ISEP, School of Engineering, Polytechnic Institute of Porto, PT
15:00 h. Integration in bioanalysis: the ivD-platform
   Prof Frank Bier, Department of Biosystems Integration and Automation, Fraunhofer Branch Bioanalysis and Bioprocessing, IZI-BB, DE
15:30 h. End User presentation (tbc)
16:00 h. Panel discussion
16:30 h. Moderator Closing Remarks
16:35 h. End of workshop

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